

Global Wafer Level Packaging Market Size Study, by Integration Type (Fan-in wafer Level Packaging, Fan-out Level Packaging) by Packaging Technology (3D TSV WLP, 5D TSV WLP, WLCSP, Nano WLP, Others) by Bumping Technology (Copper Pillar, Solder bumping, Gold bumping, Others) by Industry (Industrial, Automotive, Healthcare, Others) by Regional Forecasts 2017-2025

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Abstracts

Global Wafer Level Packaging Market valued approximately USD XXX million in 2016 is anticipated to grow with a healthy growth rate of more than XX.X% over the forecast period 2017-2025. Trending Internet of Things (IoT): a submarket of the overall electronics market

One of the major trends that will gain traction in this market is the increased adoption of semiconductor ICs in automobiles. Several automotive manufacturers have started focusing on the electrification and automation of automobiles. This will increase the need for semiconductor ICs in various products such as GPS, airbag control, anti-lock braking system (ABS), power doors and windows, car navigation and display, infotainment, collision detection technology, and automated driving and will consecutively increase the demand for packaging solutions such as fan-in wafer level packaging.

The objective of the study is to define market sizes of different segments & countries in recent years and to forecast the values to the coming eight years. The report is designed to incorporate both qualitative and quantitative aspects of the industry within each of the regions and countries involved in the study. Furthermore, the report also

caters the detailed information about the crucial aspects such as driving factors & challenges which will define the future growth of the market. Additionally, the report shall also incorporate available opportunities in micro markets for stakeholders to invest along with the detailed analysis of competitive landscape and product offerings of key players. The detailed segments and sub-segment of the market are explained below:

By Integration Type:

- Fan-in wafer level packaging

- Fan-out wafer level packaging

By Packaging Technology:

- 3D TSV WLP

- 5D TSV WLP

- WLCSP

- Nano WLP

- Others

By Bumping Technology:

- Copper pillar

- Solder Bumping

- Gold Bumping

- Others

By Industry:

Electronics

IT & Telecommunication

Industrial

Automotive

Aerospace & Defense

Healthcare

Others

By Regions:

North America

U.S.

Canada

Europe

UK

Germany

Asia Pacific

China

India

Japan

Latin America

Brazil

Mexico

Rest of the World

Furthermore, years considered for the study are as follows:

Historical year – 2015

Base year – 2016

Forecast period – 2017 to 2025

Some of the key manufacturers involved in the market are Amkor Technology, Inc., Fujitsu, Jiangsu Changjiang Electronics Technology Co. Ltd., Deca Technologies, Qualcomm Technologies. Acquisitions and effective mergers are some of the strategies adopted by the key manufacturers. New product launches and continuous technological innovations are the key strategies adopted by the major players.

Target Audience of the Global Wafer Level Packaging Market in Market Study:

Key Consulting Companies & Advisors

Large, medium-sized, and small enterprises

Venture capitalists

Value-Added Resellers (VARs)

Third-party knowledge providers

Investment bankers

Investors

Contents

CHAPTER 1. GLOBAL WAFER LEVEL PACKAGING MARKET DEFINITION AND SCOPE

- 1.1. Research Objective
- 1.2. Market Definition
- 1.3. Scope of The Study
- 1.4. Years Considered for The Study
- 1.5. Currency Conversion Rates
- 1.6. Report Limitation

CHAPTER 2. RESEARCH METHODOLOGY

- 2.1. Research Process
 - 2.1.1. Data Mining
 - 2.1.2. Analysis
 - 2.1.3. Market Estimation
 - 2.1.4. Validation
 - 2.1.5. Publishing
- 2.2. Research Assumption

CHAPTER 3. EXECUTIVE SUMMARY

- 3.1. Global & Segmental Market Estimates & Forecasts, 2015-2025 (USD Billion)
- 3.2. Key Trends

CHAPTER 4. GLOBAL WAFER LEVEL PACKAGING MARKET DYNAMICS

- 4.1. Growth Prospects
 - 4.1.1. Drivers
 - 4.1.2. Restraints
 - 4.1.3. Opportunities
- 4.2. Industry Analysis
 - 4.2.1. Porter's 5 Force Model
 - 4.2.2. PEST Analysis
 - 4.2.3. Value Chain Analysis
- 4.3. Analyst Recommendation & Conclusion

CHAPTER 5. GLOBAL WAFER LEVEL PACKAGING MARKET, BY INTEGRATION TYPE

- 5.1. Market Snapshot
- 5.2. Market Performance - Potential Model
- 5.3. Global Wafer Level Packaging Market, Sub Segment Analysis
 - 5.3.1. Fan-in wafer level packaging
 - 5.3.1.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 5.3.1.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 5.3.2. Fan-out level packaging
 - 5.3.2.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 5.3.2.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)

CHAPTER 6. GLOBAL WAFER LEVEL PACKAGING MARKET, BY PACKAGING TECHNOLOGY

- 6.1. Market Snapshot
- 6.2. Market Performance - Potential Model
- 6.3. Global Wafer Level Packaging Market, Sub Segment Analysis
 - 6.3.1. 3D TSV WLP
 - 6.3.1.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 6.3.1.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 6.3.2. 5D TSV WLP
 - 6.3.2.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 6.3.2.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 6.3.3. WLCSP
 - 6.3.3.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 6.3.3.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 6.3.4. Nano WLP
 - 6.3.4.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 6.3.4.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 6.3.5. Others
 - 6.3.5.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 6.3.5.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)

CHAPTER 7. GLOBAL WAFER LEVEL PACKAGING MARKET, BY BUMPING TECHNOLOGY

- 7.1. Market Snapshot

- 7.2. Market Performance - Potential Model
- 7.3. Global Wafer Level Packaging Market, Sub Segment Analysis
 - 7.3.1. Copper Pillar
 - 7.3.1.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 7.3.1.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 7.3.2. Solder bumping
 - 7.3.2.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 7.3.2.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 7.3.3. Gold Bumping
 - 7.3.3.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 7.3.3.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 7.3.4. Others
 - 7.3.4.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 7.3.4.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)

CHAPTER 8. GLOBAL WAFER LEVEL PACKAGING MARKET, BY INDUSTRY

- 8.1. Market Snapshot
- 8.2. Market Performance - Potential Model
- 8.3. Global Wafer Level Packaging Market, Sub Segment Analysis
 - 8.3.1. Electronics
 - 8.3.1.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 8.3.1.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 8.3.2. IT & Telecommunication
 - 8.3.2.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 8.3.2.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 8.3.3. Industry
 - 8.3.3.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 8.3.3.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 8.3.4. Automotive
 - 8.3.4.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 8.3.4.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 8.3.5. Aerospace & Defence
 - 8.3.5.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 8.3.5.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 8.3.6. Healthcare
 - 8.3.6.1. Market estimates & forecasts, 2015-2025 (USD Billion)
 - 8.3.6.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)
 - 8.3.7. Others

8.3.7.1. Market estimates & forecasts, 2015-2025 (USD Billion)

8.3.7.2. Regional breakdown estimates & forecasts, 2015-2025 (USD Billion)

CHAPTER 9. GLOBAL WAFER LEVEL PACKAGING MARKET, BY REGIONAL ANALYSIS

9.1. Wafer Level Packaging Market, Regional Market Snapshot (2015-2025)

9.2. North America Wafer Level Packaging Market Snapshot

9.2.1. U.S.

9.2.1.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.2.1.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.2.1.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.2.1.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.2.1.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.2.2. Canada

9.2.2.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.2.2.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.2.2.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.2.2.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.2.2.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3. Europe Wafer Level Packaging Market Snapshot

9.3.1. U.K.

9.3.1.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.3.1.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.1.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.1.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.1.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.2. Germany

9.3.2.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.3.2.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.2.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.2.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

Billion)

9.3.2.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.3. France

9.3.3.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.3.3.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.3.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.3.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.3.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.4. Rest of Europe

9.3.4.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.3.4.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.4.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.4.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.3.4.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4. Asia Wafer Level Packaging Market Snapshot

9.4.1. China

9.4.1.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.4.1.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.1.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.1.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.1.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.2. India

9.4.2.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.4.2.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.2.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.2.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.2.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.3. Japan

9.4.3.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.4.3.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.3.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

Billion)

9.4.3.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.3.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.4. Rest of Asia Pacific

9.4.4.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.4.4.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.4.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.4.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.4.4.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.5. Latin America Wafer Level Packaging Market Snapshot

9.5.1. Brazil

9.5.1.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.5.1.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.5.1.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.5.1.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.5.1.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.5.2. Mexico

9.5.2.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.5.2.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.5.2.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.5.2.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.5.2.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.6. Rest of The World

9.6.1. South America

9.6.1.1. Market estimates & forecasts, 2015-2025 (USD Billion)

9.6.1.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.6.1.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.6.1.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.6.1.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

9.6.2. Middle East and Africa

- 9.6.2.1. Market estimates & forecasts, 2015-2025 (USD Billion)
- 9.6.2.2. Integration Type breakdown estimates & forecasts, 2015-2025 (USD Billion)
- 9.6.2.3. Packaging Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)
- 9.6.2.4. Bumping Technology breakdown estimates & forecasts, 2015-2025 (USD Billion)
- 9.6.2.5. Industry breakdown estimates & forecasts, 2015-2025 (USD Billion)

CHAPTER 10. COMPETITIVE INTELLIGENCE

- 10.1. Company Market Share (Subject to Data Availability)
- 10.2. Top Market Strategies
- 10.3. Company Profiles
 - 10.3.1. Amkor Technology, Inc.
 - 10.3.1.1. Overview
 - 10.3.1.2. Financial (Subject to Data Availability)
 - 10.3.1.3. Product Summary
 - 10.3.1.4. Recent Developments
 - 10.3.2. Fujitsu
 - 10.3.3. Jiangsu Changjiang Electronics Technology Co.Ltd.
 - 10.3.4. Deca Technologies
 - 10.3.5. Qualcomm Technologies, Inc.
 - 10.3.6. Toshiba Corporation
 - 10.3.7. Tokyo Electron Ltd.
 - 10.3.8. Applied Materials, Inc.
 - 10.3.9. ASML Holding N.V
 - 10.3.10. Lam Research Corporation

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